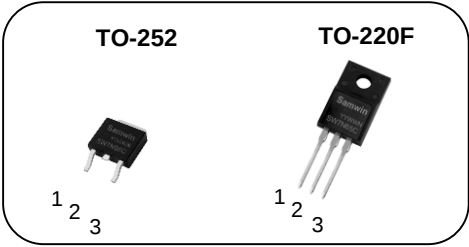


N-channel Enhanced mode TO-252/TO-220F MOSFET

Features

- High ruggedness
- Low $R_{DS(ON)}$ (Typ 1.2Ω)@ $V_{GS}=10V$
- Low Gate Charge (Typ 27nC)
- Improved dv/dt Capability
- 100% Avalanche Tested
- Application: LED, Charger, PC Power



1. Gate 2. Drain 3. Source

BV_{DSS} : 650V
I_D : 7A
R_{DS(ON)} : 1.2Ω

The circuit symbol for an N-channel MOSFET is shown. It consists of a circle with a vertical line on the left (gate), a horizontal line on the top (drain), and a horizontal line on the bottom (source). The pins are numbered 1, 2, and 3 from left to right.



General Description

This power MOSFET is produced with advanced technology of SAMWIN. This technology enable the power MOSFET to have better characteristics, including fast switching time, low on resistance, low gate charge and especially excellent avalanche characteristics.

Order Codes

Item	Sales Type	Marking	Package	Packaging
1	SW D 7N65C	SW7N65C	TO-252	REEL
2	SW F 7N65C	SW7N65C	TO-220F	TUBE

Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-252	TO-220F	
V _{DSS}	Drain to source voltage	650		V
I _D	Continuous drain current (@T _C =25°C)	7*		A
	Continuous drain current (@T _C =100°C)	4.4*		A
I _{DM}	Drain current pulsed (note 1)	28		A
V _{GS}	Gate to source voltage	±30		V
E _{AS}	Single pulsed avalanche energy (note 2)	198		mJ
E _{AR}	Repetitive avalanche energy (note 1)	20		mJ
dv/dt	Peak diode recovery dv/dt (note 3)	5		V/ns
P _D	Total power dissipation (@T _C =25°C)	169	39	W
	Derating factor above 25°C	1.35	0.3	W/°C
T _{STG} , T _J	Operating junction temperature & storage temperature	-55 ~ + 150		°C

*. Drain current is limited by junction temperature.

Thermal characteristics

Symbol	Parameter	Value		Unit
		TO-252	TO-220F	
R _{thjc}	Thermal resistance, Junction to case	0.74	3.2	°C/W
R _{thja}	Thermal resistance, Junction to ambient		48.7	°C/W

Electrical characteristic (T_j = 25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
Off characteristics						
BV _{DSS}	Drain to source breakdown voltage	V _{GS} =0V, I _D =250uA	650			V
ΔBV _{DSS} / ΔT _j	Breakdown voltage temperature coefficient	I _D =250uA, referenced to 25°C		0.6		V/°C
I _{DSS}	Drain to source leakage current	V _{DS} =650V, V _{GS} =0V			1	uA
		V _{DS} =520V, T _j =125°C			50	uA
I _{GSS}	Gate to source leakage current, forward	V _{GS} =30V, V _{DS} =0V			100	nA
	Gate to source leakage current, reverse	V _{GS} =-30V, V _{DS} =0V			-100	nA
On characteristics						
V _{GS(TH)}	Gate threshold voltage	V _{DS} =V _{GS} , I _D =250uA	2		4	V
R _{DS(ON)}	Drain to source on state resistance	V _{GS} =10V, I _D =3.5A, T _j =25°C		1.2	1.35	Ω
		V _{GS} =10V, I _D =3.5A, T _j =125°C		2.4		Ω
G _{fs}	Forward transconductance	V _{DS} =30V, I _D =3.5A		7.6		S
Dynamic characteristics						
C _{iss}	Input capacitance	V _{GS} =0V, V _{DS} =25V, f=1MHz		1168		pF
C _{oss}	Output capacitance			93		
C _{rss}	Reverse transfer capacitance			9		
t _{d(on)}	Turn on delay time	V _{DS} =325V, I _D =7A, R _G =10Ω, V _{GS} =10V (note 4,5)		13		ns
t _r	Rising time			25		
t _{d(off)}	Turn off delay time			23		
t _f	Fall time			25		
Q _g	Total gate charge	V _{DS} =520V, V _{GS} =10V, I _D =7A I _G =3mA (note 4,5)		27		nC
Q _{gs}	Gate-source charge			6		
Q _{gd}	Gate-drain charge			11		
R _g	Gate resistance	f=1MHz		2.0		Ω

Source to drain diode ratings characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I _S	Continuous source current	Integral reverse p-n Junction diode in the MOSFET			7	A
I _{SM}	Pulsed source current				28	A
V _{SD}	Diode forward voltage drop.	I _S =7A, V _{GS} =0V			1.4	V
t _{rr}	Reverse recovery time	I _S =7A, V _{GS} =0V, di _F /dt=100A/us		428		ns
Q _{rr}	Reverse recovery charge			3.1		uC

- ※. Notes
1.

Repeitative rating : pulse width limited by junction temperature.
2.

L =10mH, I_{AS} =6.3A, V_{DD}=50V, R_G=25Ω, Starting T_j = 25°C
3.

I_{SD} ≤ 7A, di/dt = 100A/us, V_{DD} ≤ BV_{DSS}, Staring T_j =25°C
4.

Pulse Test : Pulse Width ≤ 300us, duty cycle ≤ 2%.
5.

Essentially independent of operating temperature.

Fig. 1. On-state characteristics

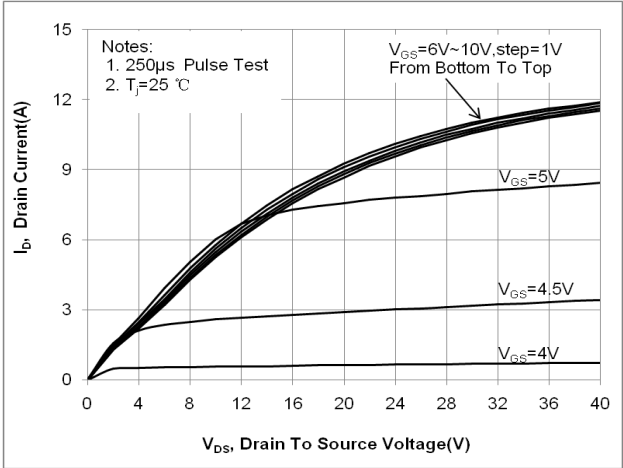


Fig. 2. Transfer Characteristics

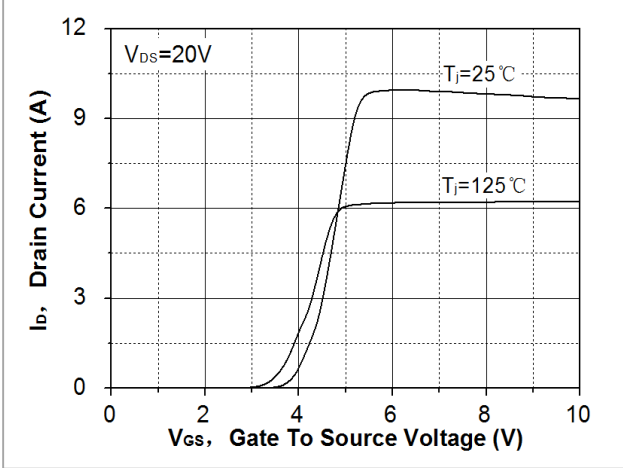


Fig. 3. On-resistance variation vs. drain current and gate voltage

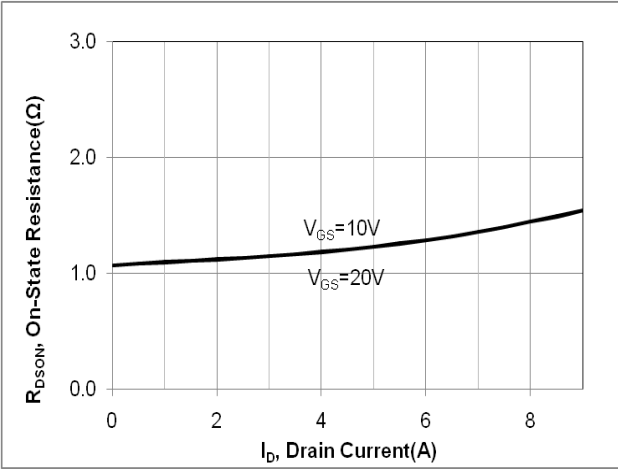


Fig. 4. On-state current vs. diode forward voltage

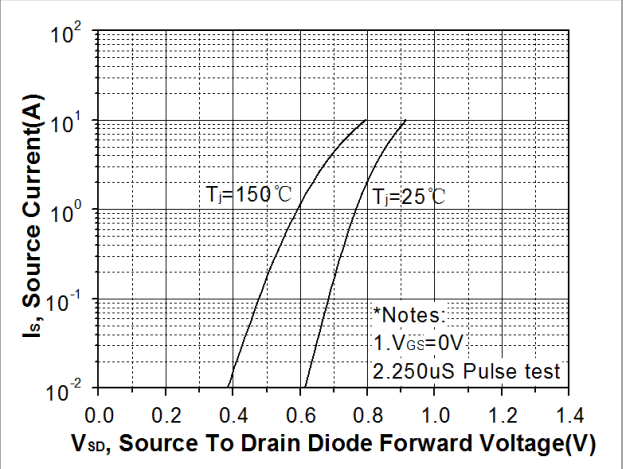


Fig 5. Breakdown voltage variation vs. junction temperature

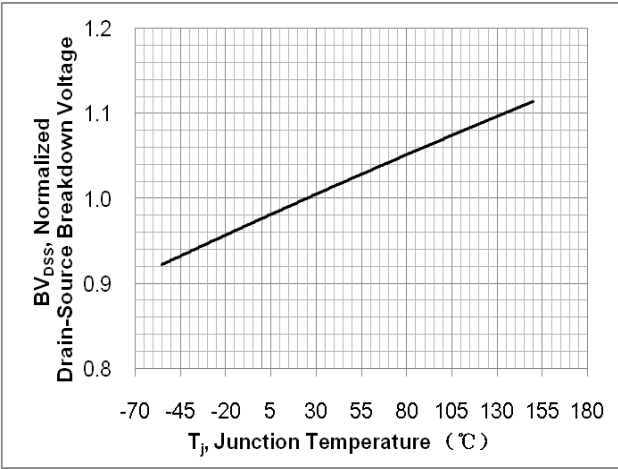


Fig. 6. On-resistance variation vs. junction temperature

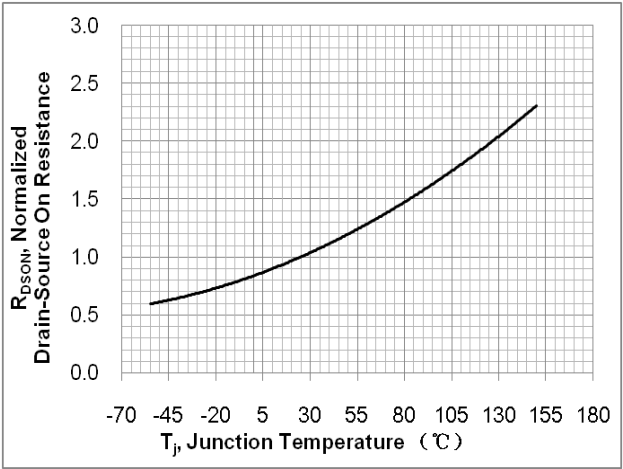


Fig. 7. Gate charge characteristics

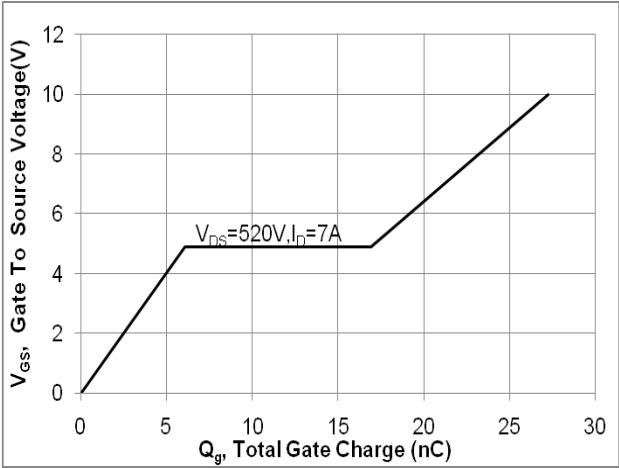


Fig. 8. Capacitance Characteristics

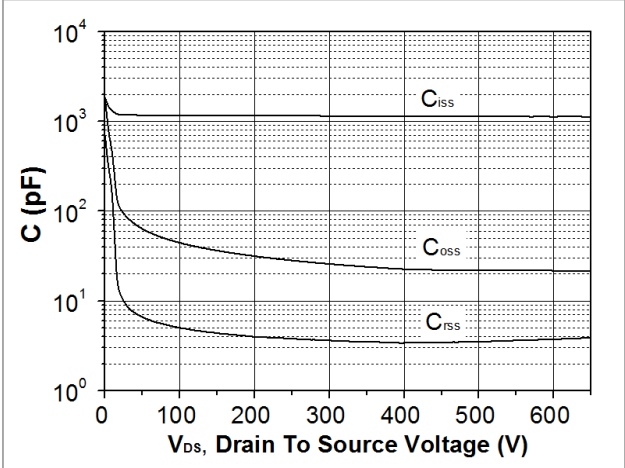


Fig. 9. Maximum safe operating area(TO-252)

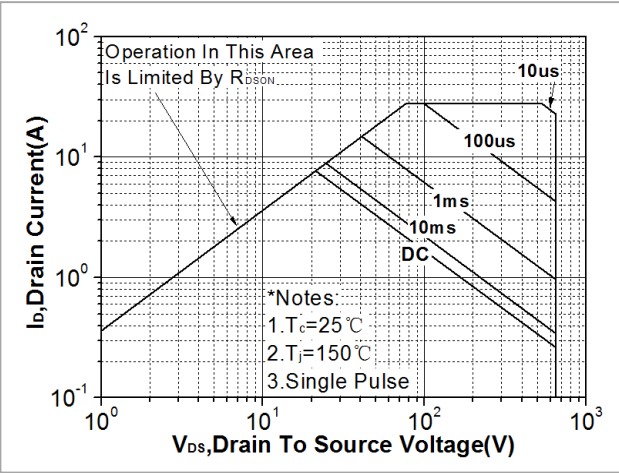


Fig. 10. Maximum safe operating area(TO-220F)

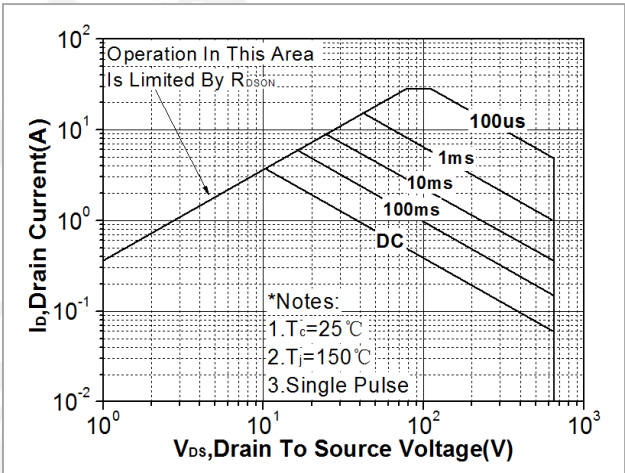


Fig. 11. Transient thermal response curve(TO-252)

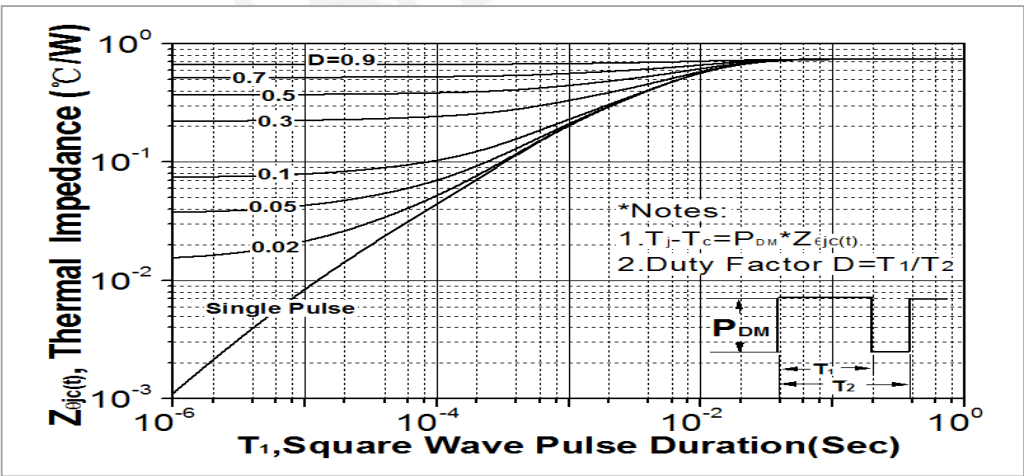


Fig. 12. Transient thermal response curve(TO-220F)

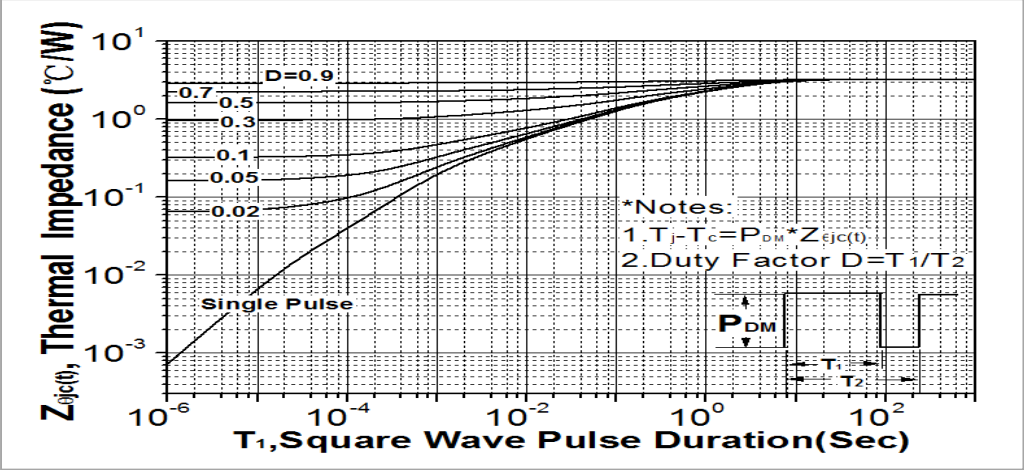


Fig. 13. Gate charge test circuit & waveform

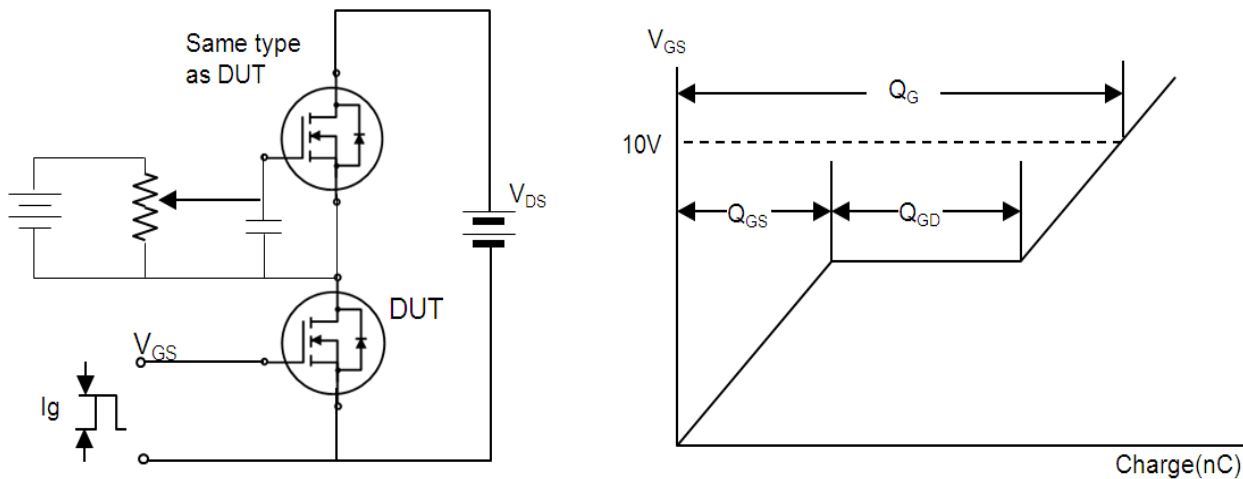


Fig. 14. Switching time test circuit & waveform

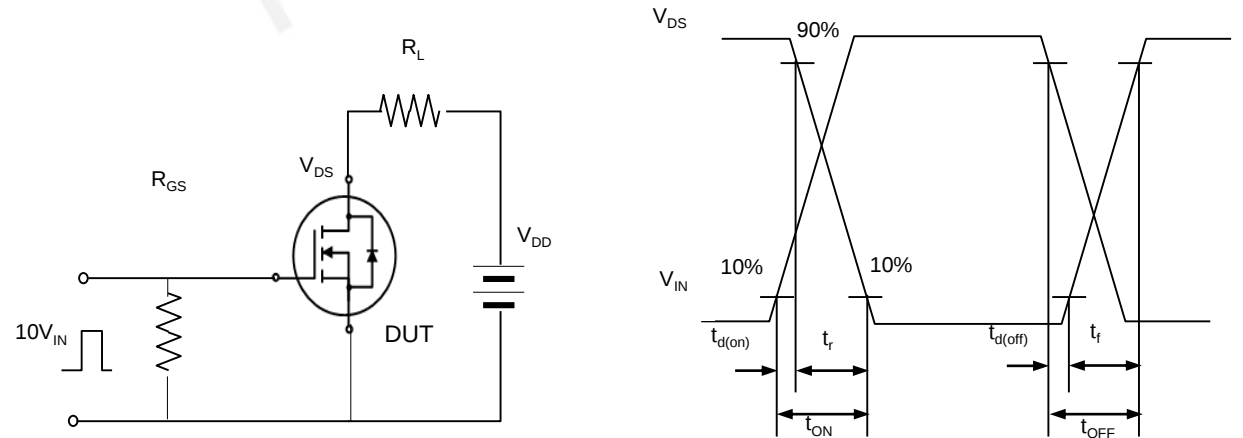


Fig. 15. Unclamped Inductive switching test circuit & waveform

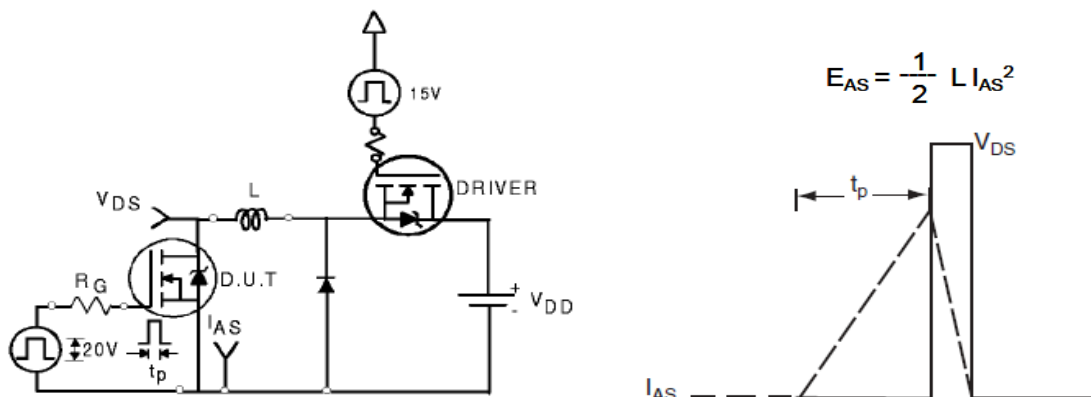
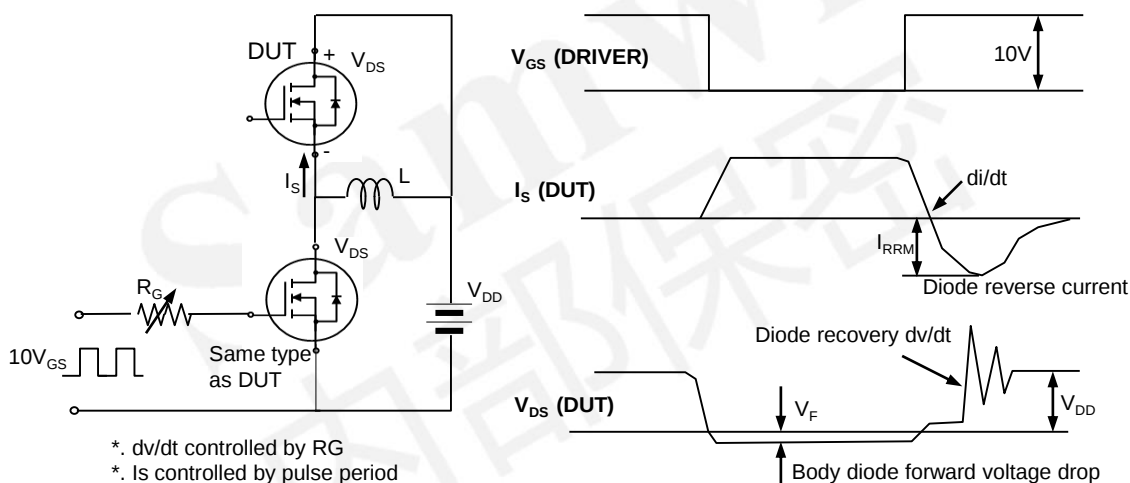


Fig. 16. Peak diode recovery dv/dt test circuit & waveform



DISCLAIMER

- * All the data & curve in this document was tested in SEMIPOWER TESTING & APPLICATION CENTER.
- * This product has passed the PCT,TC,HTRB,HTGB,HAST,PC and Solderdunk reliability testing.
- * Qualification standards can also be found on the Web site (<http://www.semipower.com.cn>)
- * Suggestions for improvement are appreciated, Please send your suggestions to samwin@samwinsemi.com